

TLV5618A

2.7-V TO 5.5-V LOW-POWER DUAL 12-BIT DIGITAL-TO-ANALOG CONVERTER WITH POWER DOWN

SLAS230H – JULY 1999 – REVISED JULY 2002

features

- Dual 12-Bit Voltage Output DAC
- Programmable Settling Time
 - 3 μ s in Fast Mode
 - 10 μ s in Slow Mode
- Compatible With TMS320 and SPI Serial Ports
- Differential Nonlinearity <0.5 LSB Typ
- Monotonic Over Temperature
- Direct Replacement for TLC5618A (C and I Suffixes)
- Available in Q-Temp Automotive HighRel Automotive Applications Configuration Control/Print Support Qualification to Automotive Standards

applications

- Digital Servo Control Loops
- Digital Offset and Gain Adjustment
- Industrial Process Control
- Machine and Motion Control Devices
- Mass Storage Devices

description

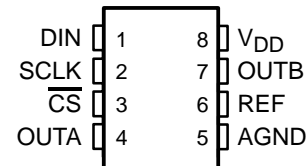
The TLV5618A is a dual 12-bit voltage output DAC with a flexible 3-wire serial interface. The serial interface is compatible with TMS320, SPI™, QSPI™, and Microwire™ serial ports. It is programmed with a 16-bit serial string containing 4 control and 12 data bits.

The resistor string output voltage is buffered by an x2 gain rail-to-rail output buffer. The buffer features a Class-AB output stage to improve stability and reduce settling time. The programmable settling time of the DAC allows the designer to optimize speed versus power dissipation.

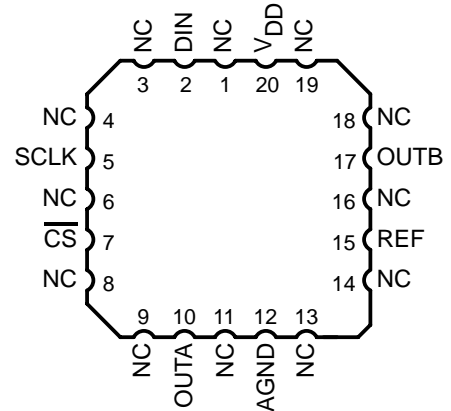
Implemented with a CMOS process, the device is designed for single supply operation from 2.7 V to 5.5 V. It is available in an 8-pin SOIC package in standard commercial and industrial temperature ranges.

The TLV5618AC is characterized for operation from 0°C to 70°C. The TLV5618AI is characterized for operation from –40°C to 85°C. The TLV5618AQ is characterized for operation from –40°C to 125°C. The TLV5618AM is characterized for operation from –55°C to 125°C.

P, D OR JG PACKAGE
(TOP VIEW)



FK PACKAGE
(TOP VIEW)



AVAILABLE OPTIONS

| T _A | PACKAGE | | | |
|----------------|-----------------|---------------------------|------------------|------------------|
| | PLASTIC DIP (P) | SOIC (D) | CERAMIC DIP (JG) | 20 PAD LCCC (FK) |
| 0°C to 70°C | TLV5618ACP | TLV5618ACD | — | — |
| –40°C to 85°C | TLV5618AIP | TLV5618AID | — | — |
| –40°C to 125°C | — | TLV5618AQD TLV5618AQDR | — | — |
| –55°C to 125°C | — | — | TLV5618AMJG | TLV5618AMFK |



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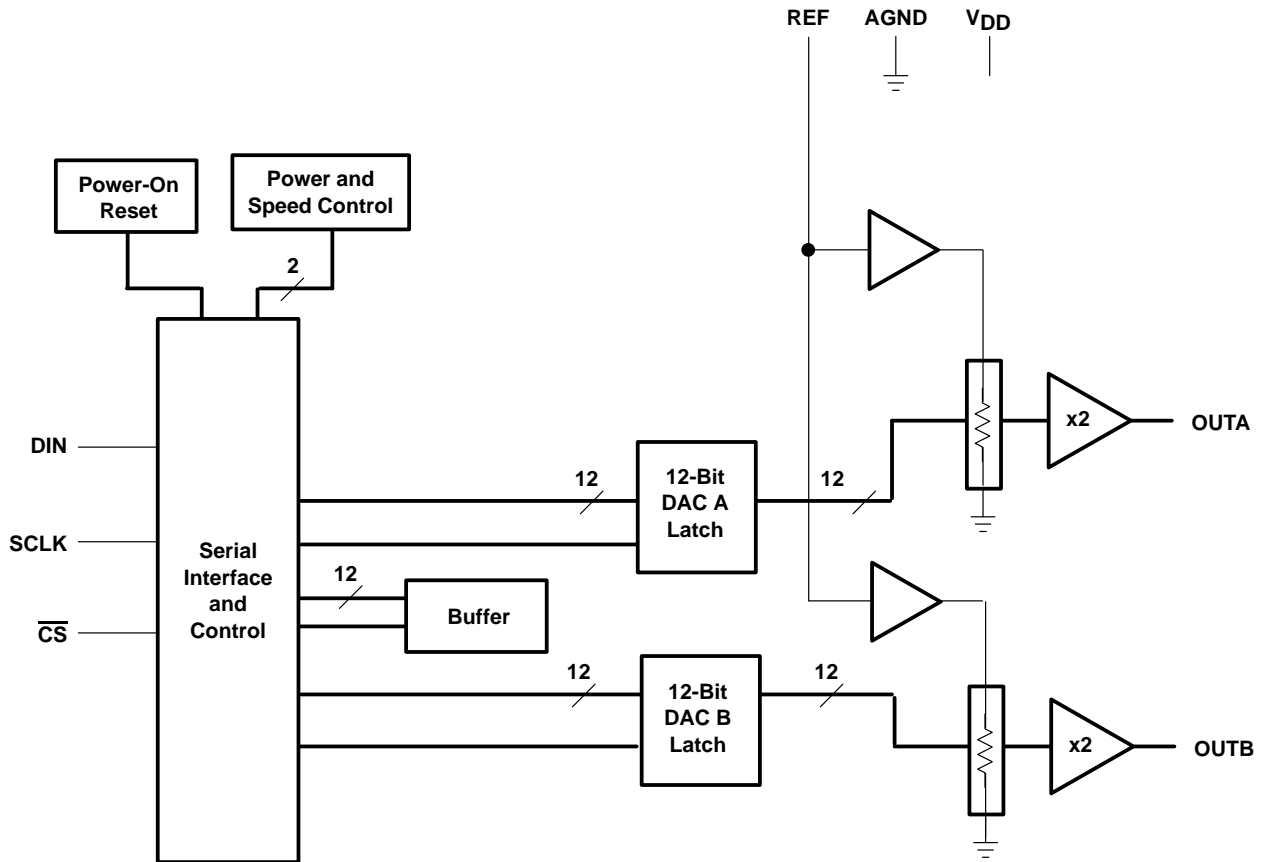
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functional block diagram



Terminal Functions

| TERMINAL NAME | NO. | I/O/P | DESCRIPTION |
|------------------------|-----|-------|---|
| AGND | 5 | P | Ground |
| $\overline{\text{CS}}$ | 3 | I | Chip select. Digital input active low, used to enable/disable inputs. |
| DIN | 1 | I | Digital serial data input |
| OUTA | 4 | O | DAC A analog voltage output |
| OUTB | 7 | O | DAC B analog voltage output |
| REF | 6 | I | Analog reference voltage input |
| SCLK | 2 | I | Digital serial clock input |
| VDD | 8 | P | Positive power supply |



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| | |
|--|-----------------------------|
| Supply voltage (V_{DD} to AGND) | 7 V |
| Reference input voltage range | – 0.3 V to $V_{DD} + 0.3$ V |
| Digital input voltage range | – 0.3 V to $V_{DD} + 0.3$ V |
| Operating free-air temperature range, T_A : TLV5618AC | 0°C to 70°C |
| TLV5618AI | –40°C to 85°C |
| TLV5618AQ | –40°C to 125°C |
| TLV5618AM | –55°C to 125°C |
| Storage temperature range, T_{stg} | –65°C to 150°C |
| Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds | 260°C |

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

| PACKAGE | $T_A \leq 25^\circ\text{C}$ POWER RATING | DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$ ‡ | $T_A = 70^\circ\text{C}$ POWER RATING | $T_A = 85^\circ\text{C}$ POWER RATING | $T_A = 125^\circ\text{C}$ POWER RATING |
|---------|---|---|--|--|---|
| D | 635 mW | 5.08 mW/°C | 407 mW | 330 mW | 127 mW |
| FK | 1375 mW | 11.00 mW/°C | 880 mW | 715 mW | 275 mW |
| JG | 1050 mW | 8.40 mW/°C | 672 mW | 546 mW | 210 mW |

‡ This is the inverse of the traditional junction-to-ambient thermal resistance ($R_{\theta JA}$). Thermal resistances are not production tested and are for informational purposes only.

recommended operating conditions

| | | MIN | NOM | MAX | UNIT |
|--|-----------------------------|------|-------|----------------|------------|
| Supply voltage, V_{DD} | $V_{DD} = 5$ V | 4.5 | 5 | 5.5 | V |
| | $V_{DD} = 3$ V | 2.7 | 3 | 3.3 | |
| Power on reset | | 0.55 | | 2 | V |
| High-level digital input voltage, V_{IH} | $V_{DD} = 2.7$ V | 2 | | | V |
| | $V_{DD} = 5.5$ V | 2.4 | | | |
| Low-level digital input voltage, V_{IL} | $V_{DD} = 2.7$ V | | | 0.6 | V |
| | $V_{DD} = 5.5$ V | | | 1 | |
| Reference voltage, V_{ref} to REF terminal | $V_{DD} = 5$ V (see Note 1) | AGND | 2.048 | $V_{DD} - 1.5$ | V |
| | $V_{DD} = 3$ V (see Note 1) | AGND | 1.024 | $V_{DD} - 1.5$ | |
| Load resistance, R_L | | 2 | | | k Ω |
| Load capacitance, C_L | | | | 100 | pF |
| Clock frequency, $f_{(CLK)}$ | | | | 20 | MHz |
| Operating free-air temperature, T_A | TLV5618AC | 0 | | 70 | °C |
| | TLV5618AI | –40 | | 85 | |
| | TLV5618AQ | –40 | | 125 | |
| | TLV5618AM | –55 | | 125 | |

NOTE 1: Due to the x2 output buffer, a reference input voltage $\geq (V_{DD} - 0.4 \text{ V})/2$ causes clipping of the transfer function.



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electrical characteristics over recommended operating conditions (unless otherwise noted)

power supply

| PARAMETER | | TEST CONDITIONS | | | MIN | TYP | MAX | UNIT |
|---------------------------|------------------------------|--|----------------------------------|----------------|------|-----|-----|------|
| I _{DD} | Power supply current | No load, All inputs = AGND or V _{DD} , DAC latch = All ones | V _{DD} = 4.5 V to 5.5 V | C & I suffixes | Fast | 1.8 | 2.5 | mA |
| | | | | | Slow | 0.8 | 1 | |
| | | | V _{DD} = 2.7 V to 3.3 V | | Fast | 1.6 | 2.2 | mA |
| | | | | | Slow | 0.6 | 0.9 | |
| | | | V _{DD} = 2.7 V to 5.5 V | M & Q suffixes | Fast | 1.8 | 2.3 | mA |
| | | | | | Slow | 0.8 | 1 | |
| Power down supply current | | | | | | 1 | μA | |
| PSRR | Power supply rejection ratio | Zero scale, See Note 2 | | | | -65 | | dB |
| | | Full scale, See Note 3 | | | | -65 | | |

- NOTES: 2. Power supply rejection ratio at zero scale is measured by varying V_{DD} and is given by:
 $PSRR = 20 \log [(E_{ZS}(V_{DDmax}) - E_{ZS}(V_{DDmin})/V_{DDmax}]$
3. Power supply rejection ratio at full scale is measured by varying V_{DD} and is given by:
 $PSRR = 20 \log [(E_G(V_{DDmax}) - E_G(V_{DDmin})/V_{DDmax}]$

static DAC specifications

| PARAMETER | | TEST CONDITIONS | | | MIN | TYP | MAX | UNIT |
|----------------------|---|-----------------|----------------|---------------------------------|-----|-------|-----|----------------|
| Resolution | | | | | 12 | | | bits |
| INL | Integral nonlinearity | See Note 4 | | | | ±2 | ±4 | LSB |
| DNL | Differential nonlinearity | See Note 5 | | | | ±0.5 | ±1 | LSB |
| E _{ZS} | Zero-scale error (offset error at zero scale) | See Note 6 | | | | | ±12 | mV |
| E _{ZS} (TC) | Zero-scale-error temperature coefficient | See Note 7 | | | | 3 | | ppm/°C |
| E _G | Gain error | See Note 8 | C & I suffixes | V _{DD} = 4.5 V – 5.5 V | | ±0.29 | | % full scale V |
| | | | | V _{DD} = 2.7 V – 3.3 V | | ±0.6 | | |
| | | | M & Q suffixes | V _{DD} = 2.7 V – 5.5 V | | ±0.6 | | |
| E _G (TC) | Gain-error temperature coefficient | See Note 9 | | | | 1 | | ppm/°C |

- NOTES: 4. The relative accuracy of integral nonlinearity (INL), sometimes referred to as linearity error, is the maximum deviation of the output from the line between zero and full scale, excluding the effects of zero-code and full-scale errors.
5. The differential nonlinearity (DNL), sometimes referred to as differential error, is the difference between the measured and ideal 1-LSB amplitude change of any two adjacent codes.
6. Zero-scale error is the deviation from zero voltage output when the digital input code is zero.
7. Zero-scale-error temperature coefficient is given by: $E_{ZS} TC = [E_{ZS}(T_{max}) - E_{ZS}(T_{min})]/2V_{ref} \times 10^6/(T_{max} - T_{min})$.
8. Gain error is the deviation from the ideal output (2V_{ref} – 1 LSB) with an output load of 10 kΩ.
9. Gain temperature coefficient is given by: $E_G TC = [E_G(T_{max}) - E_G(T_{min})]/2V_{ref} \times 10^6/(T_{max} - T_{min})$.

output specifications

| PARAMETER | | TEST CONDITIONS | | | MIN | TYP | MAX | UNIT |
|---------------------------------|----------------------|---|--|--|-----|-----|----------------------|------|
| V _O | Output voltage range | R _L = 10 kΩ | | | 0 | | V _{DD} -0.4 | V |
| Output load regulation accuracy | | V _O = 4.096 V, 2.048 V, R _L = 2 kΩ to 10 kΩ | | | | | ±0.29 | % FS |



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electrical characteristics over recommended operating conditions (unless otherwise noted)
(continued)

reference input

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|------------------------------------|---|------|----------------------|-----|------|
| V _I Input voltage range | | 0 | V _{DD} -1.5 | | V |
| R _I Input resistance | | | 10 | | MΩ |
| C _I Input capacitance | | | 5 | | pF |
| Reference input bandwidth | REF = 0.2 V _{pp} + 1.024 V dc | Fast | 1.3 | | MHz |
| | | Slow | 525 | | kHz |
| Reference feedthrough | REF = 1 V _{pp} at 1 kHz + 1.024 V dc (see Note 10) | | -80 | | dB |

NOTE 10: Reference feedthrough is measured at the DAC output with an input code = 0x000.

digital inputs

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--|----------------------------------|-----|-----|-----|------|
| I _{IH} High-level digital input current | V _I = V _{DD} | | | 1 | μA |
| I _{IL} Low-level digital input current | V _I = 0 V | -1 | | | μA |
| C _i Input capacitance | | | 8 | | pF |

analog output dynamic performance

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--|--|------|-----|-----|------|
| t _s (FS) Output settling time, full scale | R _L = 10 kΩ, C _L = 100 pF, See Note 11 | Fast | 1 | 3 | μs |
| | | Slow | 3 | 10 | |
| t _s (CC) Output settling time, code to code | R _L = 10 kΩ, C _L = 100 pF, See Note 12 | Fast | 1 | | μs |
| | | Slow | 2 | | |
| SR Slew rate | R _L = 10 kΩ, C _L = 100 pF, See Note 13 | Fast | 3 | | V/μs |
| | | Slow | 0.5 | | |
| Glitch energy | DIN = 0 to 1, FCLK = 100 kHz, CS = V _{DD} | | 5 | | nV-s |
| SNR Signal-to-noise ratio | f _s = 102 kSPS, f _{out} = 1 kHz, R _L = 10 kΩ, C _L = 100 pF | | 76 | | dB |
| SINAD Signal-to-noise + distortion | | | 68 | | |
| THD Total harmonic distortion | | | -68 | | |
| SFDR Spurious free dynamic range | | | 72 | | |

- NOTES: 11. Settling time is the time for the output signal to remain within ±0.5 LSB of the final measured value for a digital input code change of 0x020 to 0xFDF and 0xFDF to 0x020 respectively. Not tested, assured by design.
12. Settling time is the time for the output signal to remain within ±0.5 LSB of the final measured value for a digital input code change of one count. Not tested, assured by design.
13. Slew rate determines the time it takes for a change of the DAC output from 10% to 90% of full-scale voltage.



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digital input timing requirements

| | | MIN | NOM | MAX | UNIT |
|------------------|--|------------------|-----------------------|-----|------|
| $t_{su}(CS-CK)$ | Setup time, \overline{CS} low before first negative SCLK edge | C and I suffixes | $V_{DD} = 5\text{ V}$ | 5 | ns |
| | | | $V_{DD} = 3\text{ V}$ | 10 | |
| | | | Q and M suffixes | | 10 |
| $t_{su}(C16-CS)$ | Setup time, 16 th negative SCLK edge before \overline{CS} rising edge | | 10 | | ns |
| $t_w(H)$ | SCLK pulse width high | | 25 | | ns |
| $t_w(L)$ | SCLK pulse width low | | 25 | | ns |
| $t_{su}(D)$ | Setup time, data ready before SCLK falling edge | C and I suffixes | $V_{DD} = 5\text{ V}$ | 5 | ns |
| | | | $V_{DD} = 3\text{ V}$ | 10 | |
| | | | Q and M suffixes | | 8 |
| $t_h(D)$ | Hold time, data held valid after SCLK falling edge | C and I suffixes | $V_{DD} = 5\text{ V}$ | 5 | ns |
| | | | $V_{DD} = 3\text{ V}$ | 10 | |
| | | | Q and M suffixes | | 10 |
| $t_h(CSH)$ | Hold time, \overline{CS} high between cycles | | $V_{DD} = 5\text{ V}$ | 25 | ns |
| | | | $V_{DD} = 3\text{ V}$ | 50 | |

timing requirements

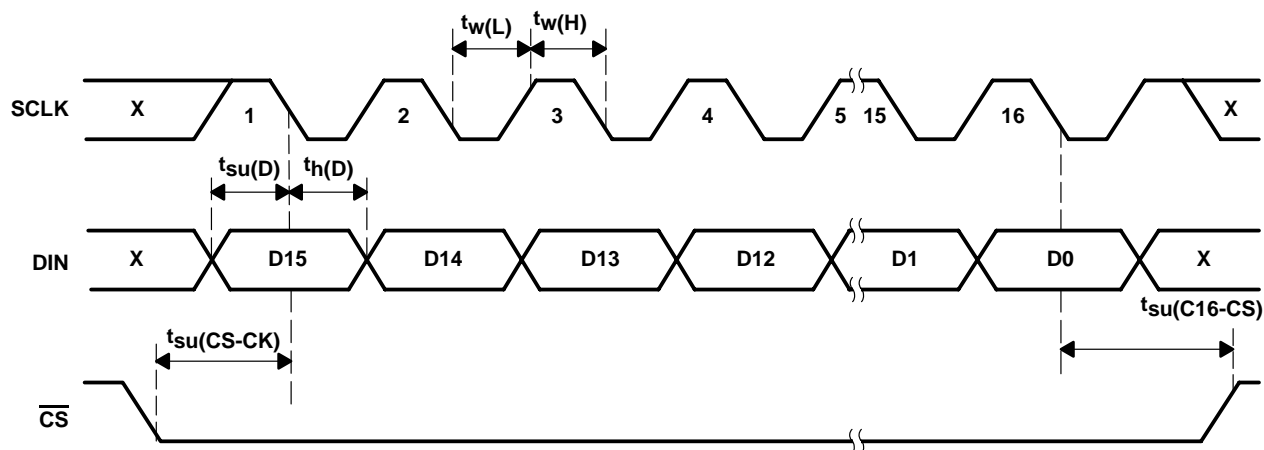


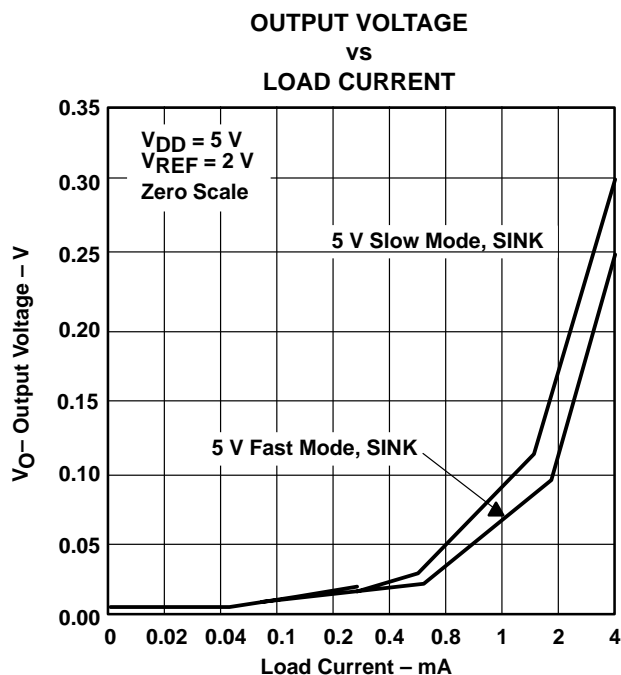
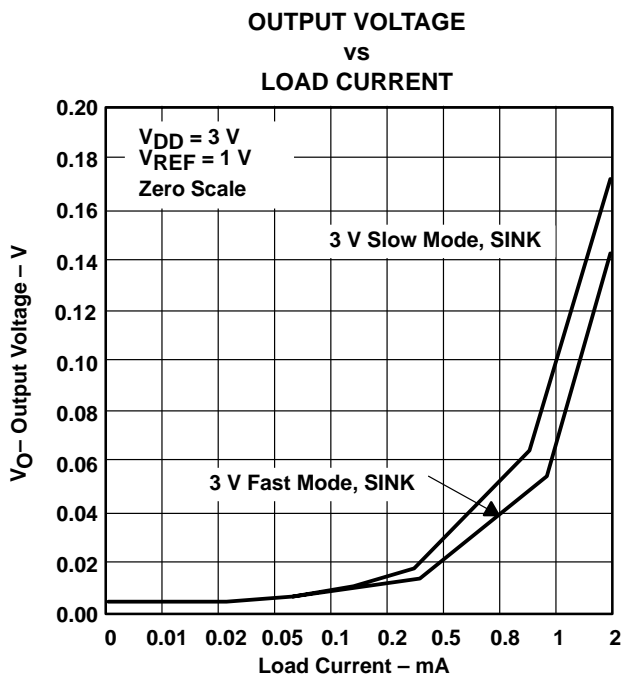
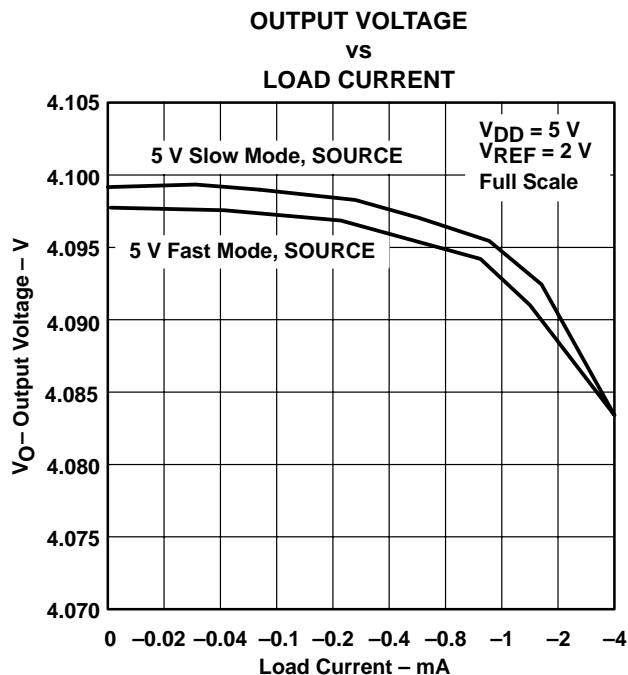
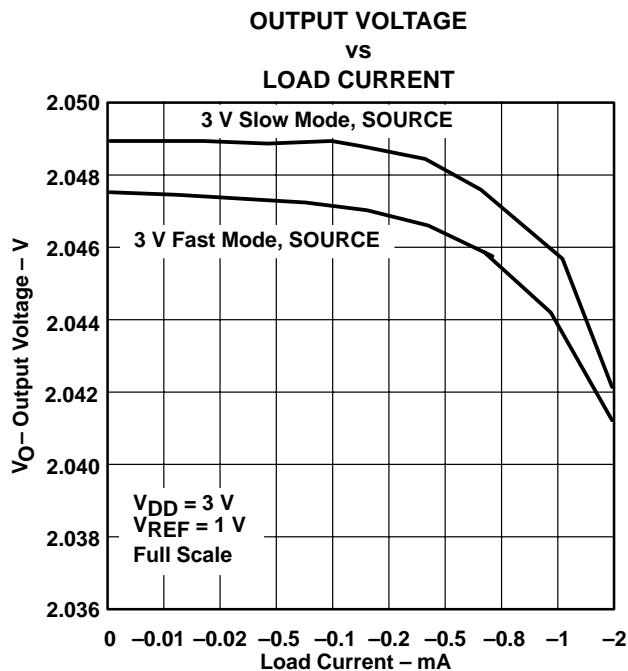
Figure 1. Timing Diagram



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TYPICAL CHARACTERISTICS



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TYPICAL CHARACTERISTICS

SUPPLY CURRENT
vs
FREE-AIR TEMPERATURE

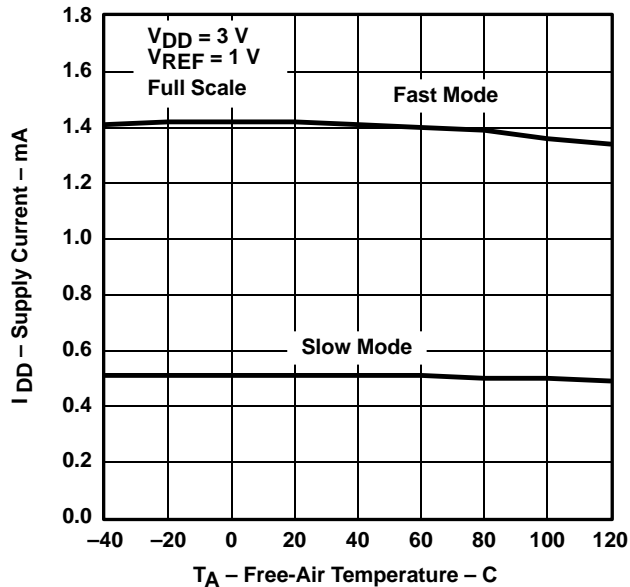


Figure 6

SUPPLY CURRENT
vs
FREE-AIR TEMPERATURE

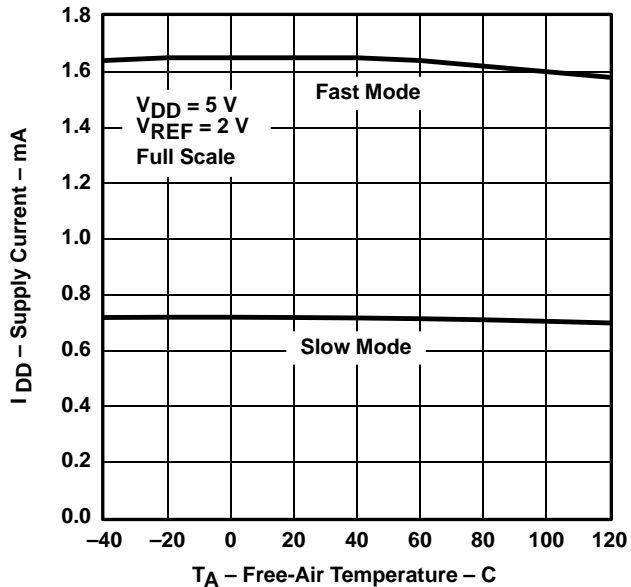


Figure 7

TOTAL HARMONIC DISTORTION
vs
FREQUENCY

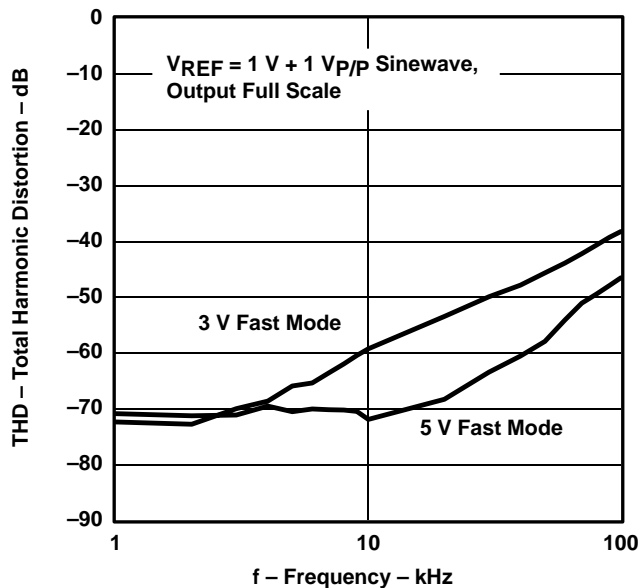


Figure 8

TOTAL HARMONIC DISTORTION
vs
FREQUENCY

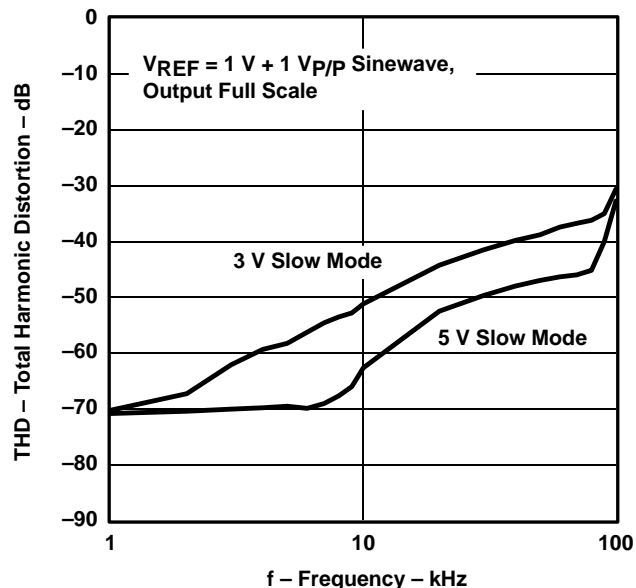


Figure 9



TYPICAL CHARACTERISTICS

INTEGRAL NONLINEARITY ERROR
vs
DIGITAL CODE

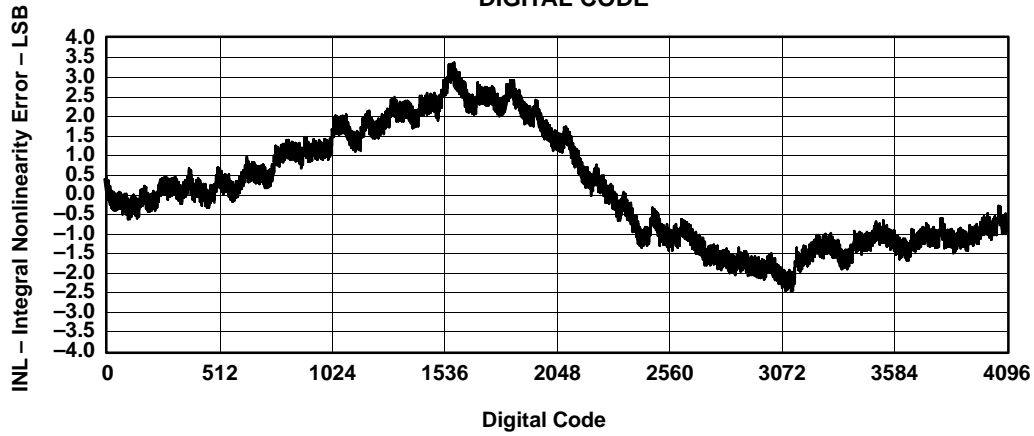


Figure 10

DIFFERENTIAL NONLINEARITY ERROR
vs
DIGITAL CODE

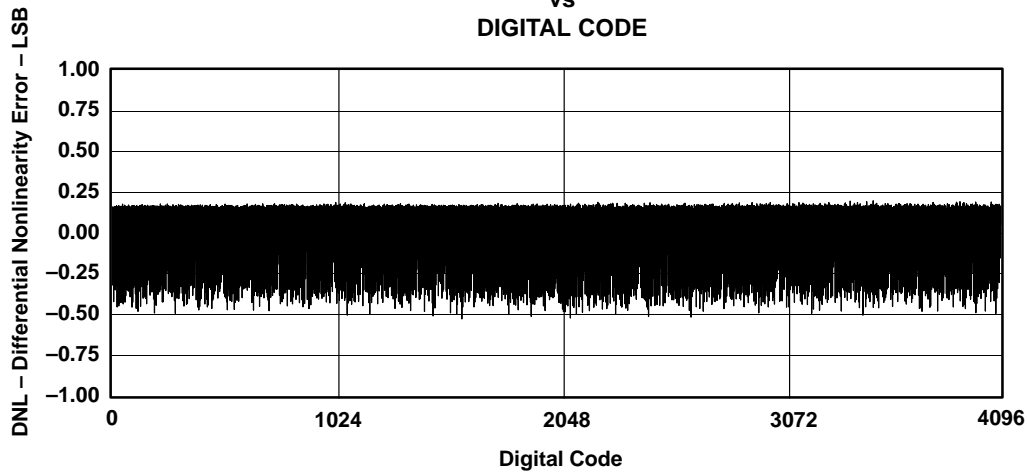


Figure 11

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APPLICATION INFORMATION

general function

The TLV5618A is a dual 12-bit, single-supply DAC, based on a resistor-string architecture. It consists of a serial interface, a speed and power down control logic, a resistor string, and a rail-to-rail output buffer.

The output voltage (full scale determined by the reference) is given by:

$$2 \text{ REF } \frac{\text{CODE}}{2^n} \text{ [V]}$$

Where REF is the reference voltage and CODE is the digital input value within the range of 0₁₀ to 2ⁿ–1, where n=12 (bits). The 16-bit data word, consisting of control bits and the new DAC value, is illustrated in the *data format* section. A power-on reset initially resets the internal latches to a defined state (all bits zero).

serial interface

A falling edge of $\overline{\text{CS}}$ starts shifting the data bit-per-bit (starting with the MSB) to the internal register on the falling edges of SCLK. After 16 bits have been transferred or $\overline{\text{CS}}$ rises, the content of the shift register is moved to the target latches (DAC A, DAC B, BUFFER, CONTROL), depending on the control bits within the data word.

Figure 12 shows examples of how to connect the TLV5618A to TMS320, SPI, and Microwire.

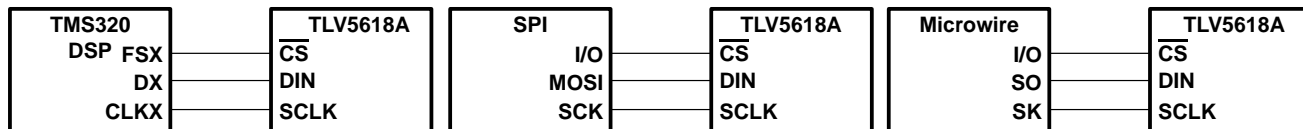


Figure 12. Three-Wire Interface

Notes on SPI and Microwire: Before the controller starts the data transfer, the software has to generate a falling edge on the pin connected to $\overline{\text{CS}}$. If the word width is 8 bits (SPI and Microwire) two write operations must be performed to program the TLV5618A. After the write operation(s), the holding registers or the control register are updated automatically on the next positive clock edge following the 16th falling clock edge.

serial clock frequency and update rate

The maximum serial clock frequency is given by:

$$f_{\text{sclkmax}} = \frac{1}{t_{\text{whmin}} + t_{\text{wlmin}}} = 20 \text{ MHz}$$

The maximum update rate is:

$$f_{\text{updatemax}} = \frac{1}{16 (t_{\text{whmin}} + t_{\text{wlmin}})} = 1.25 \text{ MHz}$$

Note that the maximum update rate is just a theoretical value for the serial interface, as the settling time of the TLV5618A should also be considered.



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APPLICATION INFORMATION

examples of operation (continued)

Both outputs are updated on the rising clock edge after D0 from the DAC A data word is sampled.

- Set power-down mode:

| D15 | D14 | D13 | D12 | D11 | D10 | D9 | D8 | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
|-----|-----|-----|-----|-----|-----|----|----|----|----|----|----|----|----|----|----|
| X | X | 1 | X | X | X | X | X | X | X | X | X | X | X | X | X |

X = Don't care

linearity, offset, and gain error using single ended supplies

When an amplifier is operated from a single supply, the voltage offset can still be either positive or negative. With a positive offset, the output voltage changes on the first code change. With a negative offset, the output voltage may not change with the first code, depending on the magnitude of the offset voltage.

The output amplifier attempts to drive the output to a negative voltage. However, because the most negative supply rail is ground, the output cannot drive below ground and clamps the output at 0 V.

The output voltage then remains at zero until the input code value produces a sufficient positive output voltage to overcome the negative offset voltage, resulting in the transfer function shown in Figure 13.

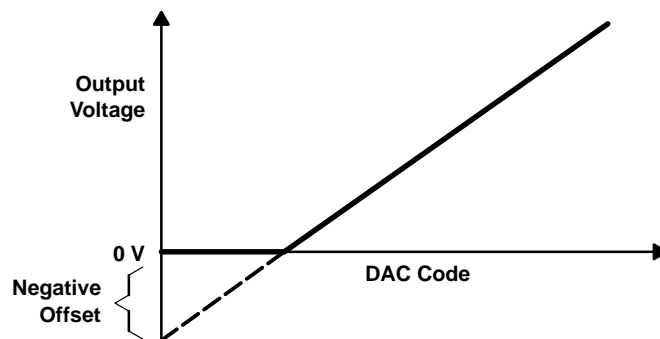


Figure 13. Effect of Negative Offset (Single Supply)

This offset error, not the linearity error, produces this breakpoint. The transfer function would have followed the dotted line if the output buffer could drive below the ground rail.

For a DAC, linearity is measured between zero-input code (all inputs 0) and full-scale code (all inputs 1) after offset and full scale are adjusted out or accounted for in some way. However, single supply operation does not allow for adjustment when the offset is negative due to the breakpoint in the transfer function. So the linearity is measured between full-scale code and the lowest code that produces a positive output voltage.

APPLICATION INFORMATION

definitions of specifications and terminology

integral nonlinearity (INL)

The relative accuracy or integral nonlinearity (INL), sometimes referred to as linearity error, is the maximum deviation of the output from the line between zero and full scale excluding the effects of zero code and full-scale errors.

differential nonlinearity (DNL)

The differential nonlinearity (DNL), sometimes referred to as differential error, is the difference between the measured and ideal 1 LSB amplitude change of any two adjacent codes. Monotonic means the output voltage changes in the same direction (or remains constant) as a change in the digital input code.

zero-scale error (E_{ZS})

Zero-scale error is defined as the deviation of the output from 0 V at a digital input value of 0.

gain error (E_G)

Gain error is the error in slope of the DAC transfer function.

total harmonic distortion (THD)

THD is the ratio of the rms value of the first six harmonic components to the value of the fundamental signal. The value for THD is expressed in decibels.

signal-to-noise ratio + distortion (S/N+D)

S/N+D is the ratio of the rms value of the output signal to the rms sum of all other spectral components below the Nyquist frequency, including harmonics but excluding dc. The value for S/N+D is expressed in decibels.

spurious free dynamic range (SFDR)

Spurious free dynamic range is the difference between the rms value of the output signal and the rms value of the largest spurious signal within a specified bandwidth. The value for SFDR is expressed in decibels.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------------------|-------------------------|
| 5962-9955701Q2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 5962-9955701Q2A TLV5618 AMFKB | Samples |
| 5962-9955701QPA | ACTIVE | CDIP | JG | 8 | 1 | TBD | Call TI | Call TI | -55 to 125 | 9955701QPA TLV5618AM | Samples |
| TLV5618ACD | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TV5618 | Samples |
| TLV5618ACDG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TV5618 | Samples |
| TLV5618ACDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TV5618 | Samples |
| TLV5618ACDRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | TV5618 | Samples |
| TLV5618ACP | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TLV5618AC | Samples |
| TLV5618ACPE4 | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | TLV5618AC | Samples |
| TLV5618AID | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TY5618 | Samples |
| TLV5618AIDG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TY5618 | Samples |
| TLV5618AIDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TY5618 | Samples |
| TLV5618AIDRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | TY5618 | Samples |
| TLV5618AIP | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | TLV5618AI | Samples |
| TLV5618AIPE4 | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | TLV5618AI | Samples |
| TLV5618AMFKB | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 5962-9955701Q2A TLV5618 AMFKB | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| TLV5618AMJG | ACTIVE | CDIP | JG | 8 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | TLV5618AMJG | Samples |
| TLV5618AMJGB | ACTIVE | CDIP | JG | 8 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 9955701QPA TLV5618AM | Samples |
| TLV5618AQD | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | V5618A | Samples |
| TLV5618AQDG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | | V5618A | Samples |
| TLV5618AQDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | V5618A | Samples |
| TLV5618AQDRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | | V5618A | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF TLV5618A, TLV5618AM :

- Catalog: [TLV5618A](#)

- Enhanced Product: [TLV5618A-EP](#), [TLV5618A-EP](#)

- Military: [TLV5618AM](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

- Enhanced Product - Supports Defense, Aerospace and Medical Applications

- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TLV5618ACDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| TLV5618AIDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| TLV5618AQDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| TLV5618AQDRG4 | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TLV5618ACDR | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 38.0 |
| TLV5618AIDR | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 38.0 |
| TLV5618AQDR | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 38.0 |
| TLV5618AQDRG4 | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 38.0 |

JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



4040107/C 08/96

- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification.
 E. Falls within MIL STD 1835 GDIP1-T8

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



| NO. OF TERMINALS ** | A | | B | |
|---------------------|------------------|------------------|------------------|------------------|
| | MIN | MAX | MIN | MAX |
| 20 | 0.342 (8,69) | 0.358 (9,09) | 0.307 (7,80) | 0.358 (9,09) |
| 28 | 0.442 (11,23) | 0.458 (11,63) | 0.406 (10,31) | 0.458 (11,63) |
| 44 | 0.640 (16,26) | 0.660 (16,76) | 0.495 (12,58) | 0.560 (14,22) |
| 52 | 0.740 (18,78) | 0.761 (19,32) | 0.495 (12,58) | 0.560 (14,22) |
| 68 | 0.938 (23,83) | 0.962 (24,43) | 0.850 (21,6) | 0.858 (21,8) |
| 84 | 1.141 (28,99) | 1.165 (29,59) | 1.047 (26,6) | 1.063 (27,0) |



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

P (R-PDIP-T8)

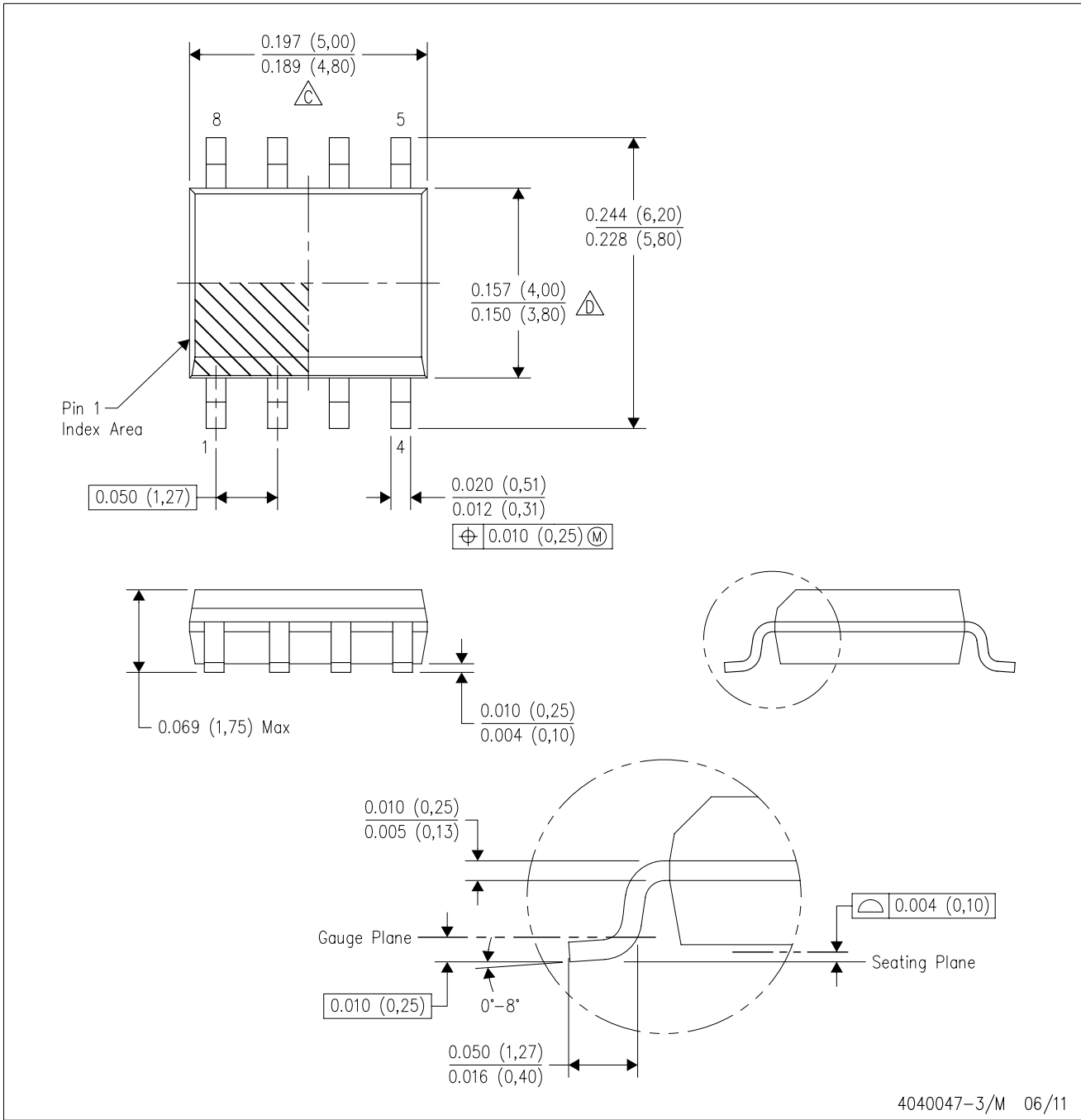
PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001 variation BA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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